# General Purpose Transistor NPN Silicon

These transistors are designed for general purpose amplifier applications. They are housed in the SOT-323/SC-70 package which is designed for low power surface mount applications.

#### Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V <sub>CEO</sub>	40	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	75	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	Ι <sub>C</sub>	600	mAdc

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board $T_A = 25^{\circ}C$	PD	150	mW
Thermal Resistance, Junction-to-Ambient	$R_{\thetaJA}$	280	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

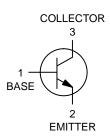


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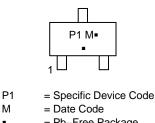
www.onsemi.com



CASE 419 STYLE 3



### MARKING DIAGRAM



= Pb-Free Package

(Note: Microdot may be in either location)

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT2222AWT1G	SC–70 (Pb–Free)	3,000 / Tape & Reel
SMMBT2222AWT1G	SC–70 (Pb–Free)	3,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (Note 1) ( $I_C = 10 \text{ mAdc}, I_B = 0$ )	V <sub>(BR)CEO</sub>	40	_	Vdc
Collector – Base Breakdown Voltage $(I_C = 10 \ \mu Adc, I_E = 0)$	V <sub>(BR)CBO</sub>	75	_	Vdc
Emitter – Base Breakdown Voltage $(I_E = 10 \ \mu Adc, I_C = 0)$	V <sub>(BR)EBO</sub>	6.0	_	Vdc
Base Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>EB</sub> = 3.0 Vdc)	I <sub>BL</sub>	-	20	nAdc
Collector Cutoff Current ( $V_{CE} = 60 \text{ Vdc}, V_{EB} = 3.0 \text{ Vdc}$ )	I <sub>CEX</sub>	_	10	nAdc
ON CHARACTERISTICS (Note 1)				
$ \begin{array}{l} \text{DC Current Gain (Note 1)} \\ (I_{C} = 0.1 \text{ mAdc, } V_{CE} = 10 \text{ Vdc}) \\ (I_{C} = 1.0 \text{ mAdc, } V_{CE} = 10 \text{ Vdc}) \\ (I_{C} = 10 \text{ mAdc, } V_{CE} = 10 \text{ Vdc}) \\ (I_{C} = 150 \text{ mAdc, } V_{CE} = 10 \text{ Vdc}) \\ (I_{C} = 500 \text{ mAdc, } V_{CE} = 10 \text{ Vdc}) \\ (I_{C} = 500 \text{ mAdc, } V_{CE} = 10 \text{ Vdc}) \end{array} $	H <sub>FE</sub>	35 50 75 100 40	- - 300 -	-
Collector – Emitter Saturation Voltage (Note 1) ( $I_C = 150 \text{ mAdc}$ , $I_B = 15 \text{ mAdc}$ ) ( $I_C = 500 \text{ mAdc}$ , $I_B = 50 \text{ mAdc}$ )	V <sub>CE(sat)</sub>	-	0.3 1.0	Vdc
Base – Emitter Saturation Voltage (Note 1) ( $I_C = 150 \text{ mAdc}$ , $I_B = 15 \text{ mAdc}$ ) ( $I_C = 500 \text{ mAdc}$ , $I_B = 50 \text{ mAdc}$ )	V <sub>BE(sat)</sub>	0.6	1.2 2.0	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Current–Gain – Bandwidth Product (I <sub>C</sub> = 20 mAdc, V <sub>CE</sub> = 20 Vdc, f = 100 MHz)	f <sub>T</sub>	300	_	MHz
Output Capacitance ( $V_{CB} = 10 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz}$ )	C <sub>obo</sub>	_	8.0	pF
Input Capacitance (V <sub>EB</sub> = 0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)	C <sub>ibo</sub>	_	30	pF
Input Impedance (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 kHz)	h <sub>ie</sub>	0.25	1.25	kΩ
Voltage Feedback Ratio (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 kHz)	h <sub>re</sub>	_	4.0	X 10 <sup>-4</sup>
Small – Signal Current Gain (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 kHz)	h <sub>fe</sub>	75	375	-
Output Admittance (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 10 mAdc, f = 1.0 kHz)	h <sub>oe</sub>	25	200	μmhos
Noise Figure (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 100 μAdc, R <sub>S</sub> = 1.0 kΩ, f = 1.0 kHz)	NF	_	4.0	dB
SWITCHING CHARACTERISTICS				
Dolov Timo			4.0	

Delay Time	(V <sub>CC</sub> = 3.0 Vdc, V <sub>BE</sub> = -0.5 Vdc,	t <sub>d</sub>	-	10	ns
Rise Time	$I_{\rm C} = 150 {\rm mAdc},  I_{\rm B1} = 15 {\rm mAdc})$	tr	-	25	
Storage Time	(V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc,	ts	-	225	ns
Fall Time	I <sub>B1</sub> = I <sub>B2</sub> = 15 mAdc)	t <sub>f</sub>	-	60	115

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2.0%.

### SWITCHING TIME EQUIVALENT TEST CIRCUITS

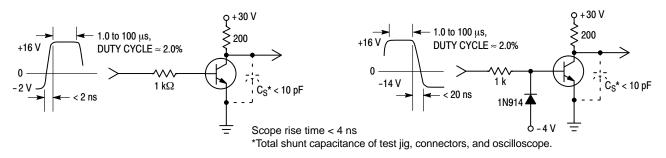
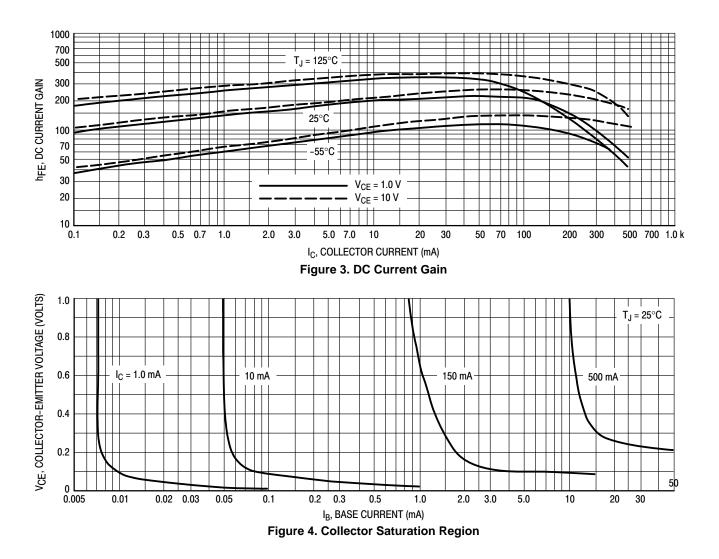




Figure 2. Turn-Off Time



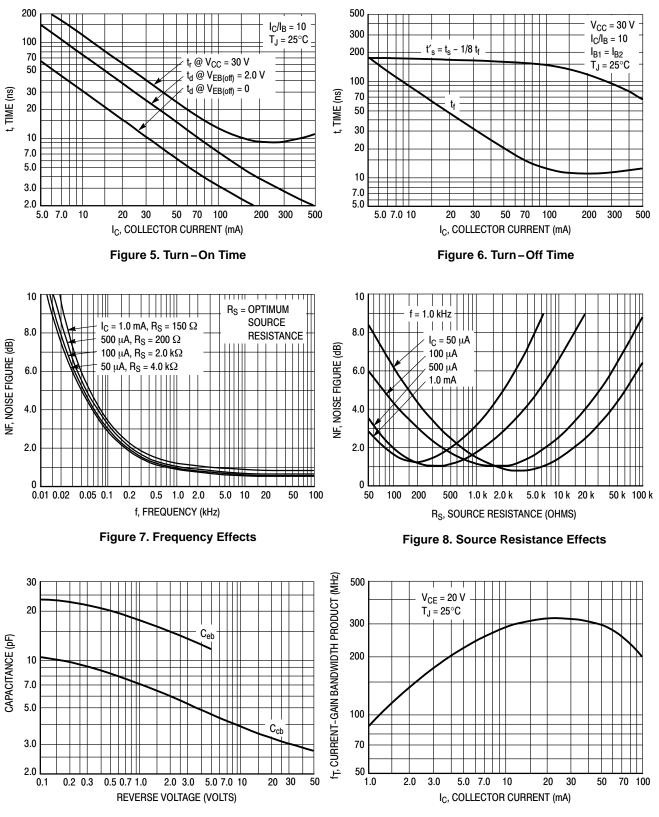
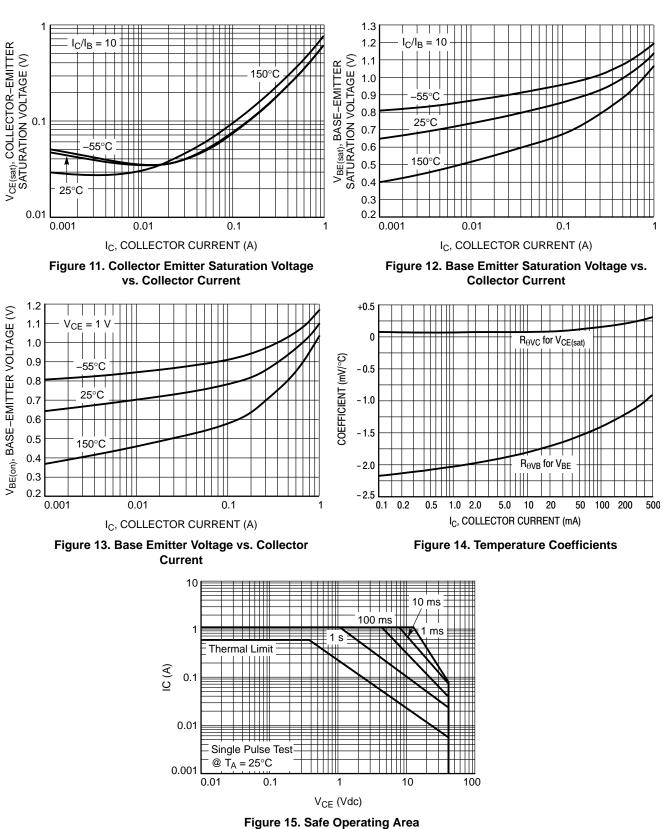
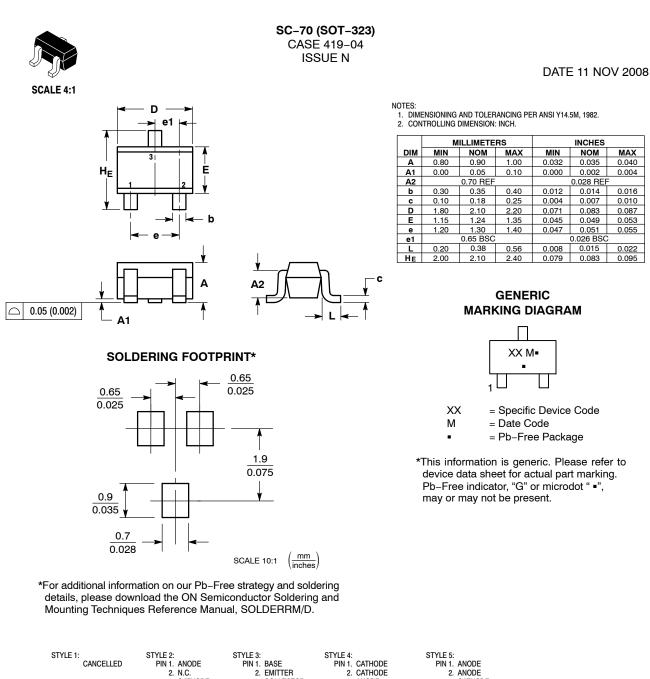


Figure 9. Capacitances

Figure 10. Current–Gain Bandwidth Product







	3. CATHODE	3. COLLECTOR	3. ANODE	3. CATHODE	
Style 6:	STYLE 7:	STYLE 8:	STYLE 9:	Style 10:	STYLE 11:
Pin 1. Emitter	PIN 1. BASE	PIN 1. GATE	Pin 1. Anode	Pin 1. Cathode	PIN 1. CATHODE
2. Base	2. EMITTER	2. SOURCE	2. Cathode	2. Anode	2. CATHODE
3. Collector	3. COLLECTOR	3. DRAIN	3. Cathode-Anode	3. Anode-Cathode	3. CATHODE

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